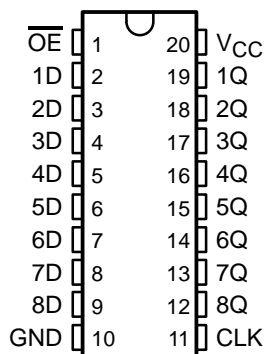


# SN54AHC574, SN74AHC574 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

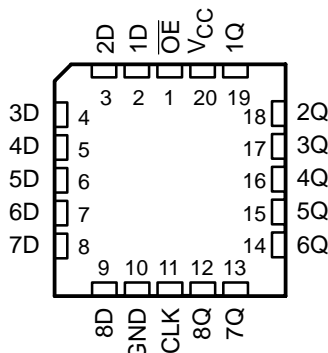
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- Operating Range 2-V to 5.5-V  $V_{CC}$
- 3-State Outputs Drive Bus Lines Directly
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

SN54AHC574 . . . J OR W PACKAGE  
SN74AHC574 . . . DB, DGV, DW, N, NS, OR PW PACKAGE  
(TOP VIEW)



SN54AHC574 . . . FK PACKAGE  
(TOP VIEW)



## description/ordering information

The 'AHC574 devices are octal edge-triggered D-type flip-flops that feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. These devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels of the data (D) inputs.

A buffered output-enable ( $\overline{OE}$ ) input places the eight outputs in either a normal logic state (high or low) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without interface or pullup components.

## ORDERING INFORMATION

T <sub>A</sub>	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube	SN74AHC574N	SN74AHC574N
	SOIC – DW	Tube	SN74AHC574DW	AHC574
		Tape and reel	SN74AHC574DWR	
	SOP – NS	Tape and reel	SN74AHC574NSR	AHC574
	SSOP – DB	Tape and reel	SN74AHC574DBR	HA574
	TSSOP – PW	Tube	SN74AHC574PW	HA574
		Tape and reel	SN74AHC574PWR	
TVSOP – DGV	Tape and reel	SN74AHC574DGVR	HA574	
–55°C to 125°C	CDIP – J	Tube	SNJ54AHC574J	SNJ54AHC574J
	CFP – W	Tube	SNJ54AHC574W	SNJ54AHC574W
	LCCC – FK	Tube	SNJ54AHC574FK	SNJ54AHC574FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
INSTRUMENTS**

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# SN54AHC574, SN74AHC574 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

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## description/ordering information (continued)

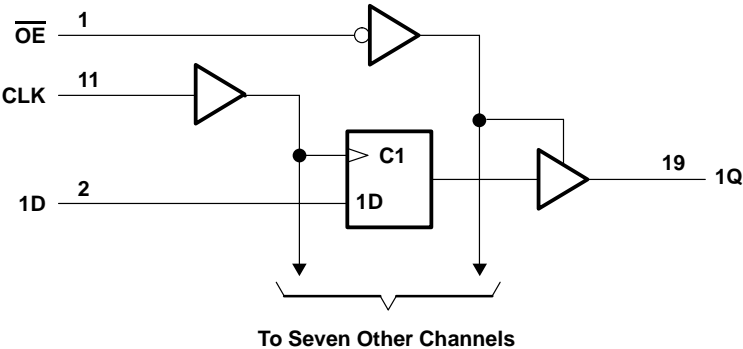
$\overline{OE}$  does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

FUNCTION TABLE  
(each flip-flop)

INPUTS			OUTPUT
$\overline{OE}$	CLK	D	Q
L	$\uparrow$	H	H
L	$\uparrow$	L	L
L	H or L	X	$Q_0$
H	X	X	Z

## logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, $V_{CC}$	–0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1)	–0.5 V to 7 V
Output voltage range, $V_O$ (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	–20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ )	±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±25 mA
Continuous current through $V_{CC}$ or GND	±75 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2):	
DB package	70°C/W
DGV package	92°C/W
DW package	58°C/W
N package	69°C/W
NS package	60°C/W
PW package	83°C/W
Storage temperature range, $T_{stg}$	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.

# SN54AHC574, SN74AHC574

## OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS

### WITH 3-STATE OUTPUTS

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#### recommended operating conditions (see Note 3)

			SN54AHC574		SN74AHC574		UNIT
			MIN	MAX	MIN	MAX	
V <sub>CC</sub>	Supply voltage		2	5.5	2	5.5	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2 V	1.5		1.5		V
		V <sub>CC</sub> = 3 V	2.1		2.1		
		V <sub>CC</sub> = 5.5 V	3.85		3.85		
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2 V		0.5		0.5	V
		V <sub>CC</sub> = 3 V		0.9		0.9	
		V <sub>CC</sub> = 5.5 V		1.65		1.65	
V <sub>I</sub>	Input voltage		0	5.5	0	5.5	V
V <sub>O</sub>	Output voltage		0	V <sub>CC</sub>	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 2 V		–50		–50	μA
		V <sub>CC</sub> = 3.3 V ± 0.3 V		–4		–4	mA
		V <sub>CC</sub> = 5 V ± 0.5 V		–8		–8	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2 V		50		50	μA
		V <sub>CC</sub> = 3.3 V ± 0.3 V		4		4	mA
		V <sub>CC</sub> = 5 V ± 0.5 V		8		8	
Δt/Δv	Input transition rise or fall rate	V <sub>CC</sub> = 3.3 V ± 0.3 V		100		100	ns/V
		V <sub>CC</sub> = 5 V ± 0.5 V		20		20	
T <sub>A</sub>	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54AHC574		SN74AHC574		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = –50 μA	2 V	1.9	2		1.9		1.9		V
		3 V	2.9	3		2.9		2.9		
		4.5 V	4.4	4.5		4.4		4.4		
	I <sub>OH</sub> = –4 mA	3 V	2.58			2.48		2.48		
	I <sub>OH</sub> = –8 mA	4.5 V	3.94			3.8		3.8		
V <sub>OL</sub>	I <sub>OL</sub> = 50 μA	2 V			0.1		0.1		0.1	V
		3 V			0.1		0.1		0.1	
		4.5 V			0.1		0.1		0.1	
	I <sub>OL</sub> = 4 mA	3 V			0.36		0.5		0.44	
	I <sub>OL</sub> = 8 mA	4.5 V			0.36		0.5		0.44	
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	0 V to 5.5 V			±0.1		±1*		±1	μA
I <sub>OZ</sub>	V <sub>O</sub> = V <sub>CC</sub> or GND	5.5 V			±0.25		±2.5		±2.5	μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V			4		40		40	μA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		3	10				10	pF
C <sub>o</sub>	V <sub>O</sub> = V <sub>CC</sub> or GND	5 V		3						pF

\* On products compliant to MIL-PRF-38535, this parameter is not production tested at V<sub>CC</sub> = 0 V.



# SN54AHC574, SN74AHC574

## OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS

### WITH 3-STATE OUTPUTS

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**timing requirements over recommended operating free-air temperature range,  
V<sub>CC</sub> = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)**

		T <sub>A</sub> = 25°C		SN54AHC574		SN74AHC574		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>w</sub>	Pulse duration, CLK high or low	5		5		5		ns
t <sub>su</sub>	Setup time, data before CLK↑	3.5		3.5		3.5		ns
t <sub>h</sub>	Hold time, data after CLK↑	1.5		1.5		1.5		ns

**timing requirements over recommended operating free-air temperature range,  
V<sub>CC</sub> = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)**

		T <sub>A</sub> = 25°C		SN54AHC574		SN74AHC574		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>w</sub>	Pulse duration, CLK high or low	5		5		5		ns
t <sub>su</sub>	Setup time, data before CLK↑	3		3		3		ns
t <sub>h</sub>	Hold time, data after CLK↑	1.5		1.5		1.5		ns

**switching characteristics over recommended operating free-air temperature range,  
V<sub>CC</sub> = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T <sub>A</sub> = 25°C			SN54AHC574		SN74AHC574		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>			C <sub>L</sub> = 15 pF	80*	125*		65*		65		MHz
			C <sub>L</sub> = 50 pF	50	75		45		45		
t <sub>PLH</sub>	CLK	Q	C <sub>L</sub> = 15 pF	8.5*	13.2*		1*	15.5*	1	15.5	ns
t <sub>PHL</sub>				8.5*	13.2*		1*	15.5*	1	15.5	
t <sub>PZH</sub>	$\overline{OE}$	Q	C <sub>L</sub> = 15 pF	8.2*	12.8*		1*	15*	1	15	ns
t <sub>PZL</sub>				8.2*	12.8*		1*	15*	1	15	
t <sub>PHZ</sub>	$\overline{OE}$	Q	C <sub>L</sub> = 15 pF	8.5*	13*		1*	15*	1	15	ns
t <sub>PLZ</sub>				8.5*	13*		1*	15*	1	15	
t <sub>PLH</sub>	CLK	Q	C <sub>L</sub> = 50 pF	11	16.7		1	19	1	19	ns
t <sub>PHL</sub>				11	16.7		1	19	1	19	
t <sub>PZH</sub>	$\overline{OE}$	Q	C <sub>L</sub> = 50 pF	10.7	16.3		1	18.5	1	18.5	ns
t <sub>PZL</sub>				10.7	16.3		1	18.5	1	18.5	
t <sub>PHZ</sub>	$\overline{OE}$	Q	C <sub>L</sub> = 50 pF	11	15		1	17	1	17	ns
t <sub>PLZ</sub>				11	15		1	17	1	17	
t <sub>sk(o)</sub>			C <sub>L</sub> = 50 pF		1.5**				1.5		ns

\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

\*\* On products compliant to MIL-PRF-38535, this parameter does not apply.



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# SN54AHC574, SN74AHC574 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range,  
 $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54AHC574		SN74AHC574		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$f_{\text{max}}$			$C_L = 15\text{ pF}$	130*	180*		110*		110		MHz
			$C_L = 50\text{ pF}$	85	115		75		75		
$t_{\text{PLH}}$	CLK	Q	$C_L = 15\text{ pF}$		5.6*	8.6*	1*	10*	1	10	ns
$t_{\text{PHL}}$					5.6*	8.6*	1*	10*	1	10	
$t_{\text{PZH}}$	$\overline{\text{OE}}$	Q	$C_L = 15\text{ pF}$		5.9*	9*	1*	10.5*	1	10.5	ns
$t_{\text{PZL}}$					5.9*	9*	1*	10.5*	1	10.5	
$t_{\text{PHZ}}$	$\overline{\text{OE}}$	Q	$C_L = 15\text{ pF}$		5.5*	9*	1*	10.5*	1	10.5	ns
$t_{\text{PLZ}}$					5.5*	9*	1*	10.5*	1	10.5	
$t_{\text{PLH}}$	CLK	Q	$C_L = 50\text{ pF}$		7.1	10.6	1	12	1	12	ns
$t_{\text{PHL}}$					7.1	10.6	1	12	1	12	
$t_{\text{PZH}}$	$\overline{\text{OE}}$	Q	$C_L = 50\text{ pF}$		7.4	11	1	12.5	1	12.5	ns
$t_{\text{PZL}}$					7.4	11	1	12.5	1	12.5	
$t_{\text{PHZ}}$	$\overline{\text{OE}}$	Q	$C_L = 50\text{ pF}$		7.1	10.1	1	11.5	1	11.5	ns
$t_{\text{PLZ}}$					7.1	10.1	1	11.5	1	11.5	
$t_{\text{sk(o)}}$			$C_L = 50\text{ pF}$			1**				1	ns

\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

\*\* On products compliant to MIL-PRF-38535, this parameter does not apply.

noise characteristics,  $V_{CC} = 5\text{ V}$ ,  $C_L = 50\text{ pF}$ ,  $T_A = 25^\circ\text{C}$  (see Note 4)

PARAMETER		SN74AHC574		UNIT
		MIN	MAX	
$V_{\text{OL(P)}}$	Quiet output, maximum dynamic $V_{\text{OL}}$		0.8	V
$V_{\text{OL(V)}}$	Quiet output, minimum dynamic $V_{\text{OL}}$		-0.8	V
$V_{\text{OH(V)}}$	Quiet output, minimum dynamic $V_{\text{OH}}$	4.2		V
$V_{\text{IH(D)}}$	High-level dynamic input voltage	3.5		V
$V_{\text{IL(D)}}$	Low-level dynamic input voltage		1.5	V

NOTE 4: Characteristics are for surface-mount packages only.

operating characteristics,  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
$C_{\text{pd}}$ Power dissipation capacitance	No load, $f = 1\text{ MHz}$	28	pF

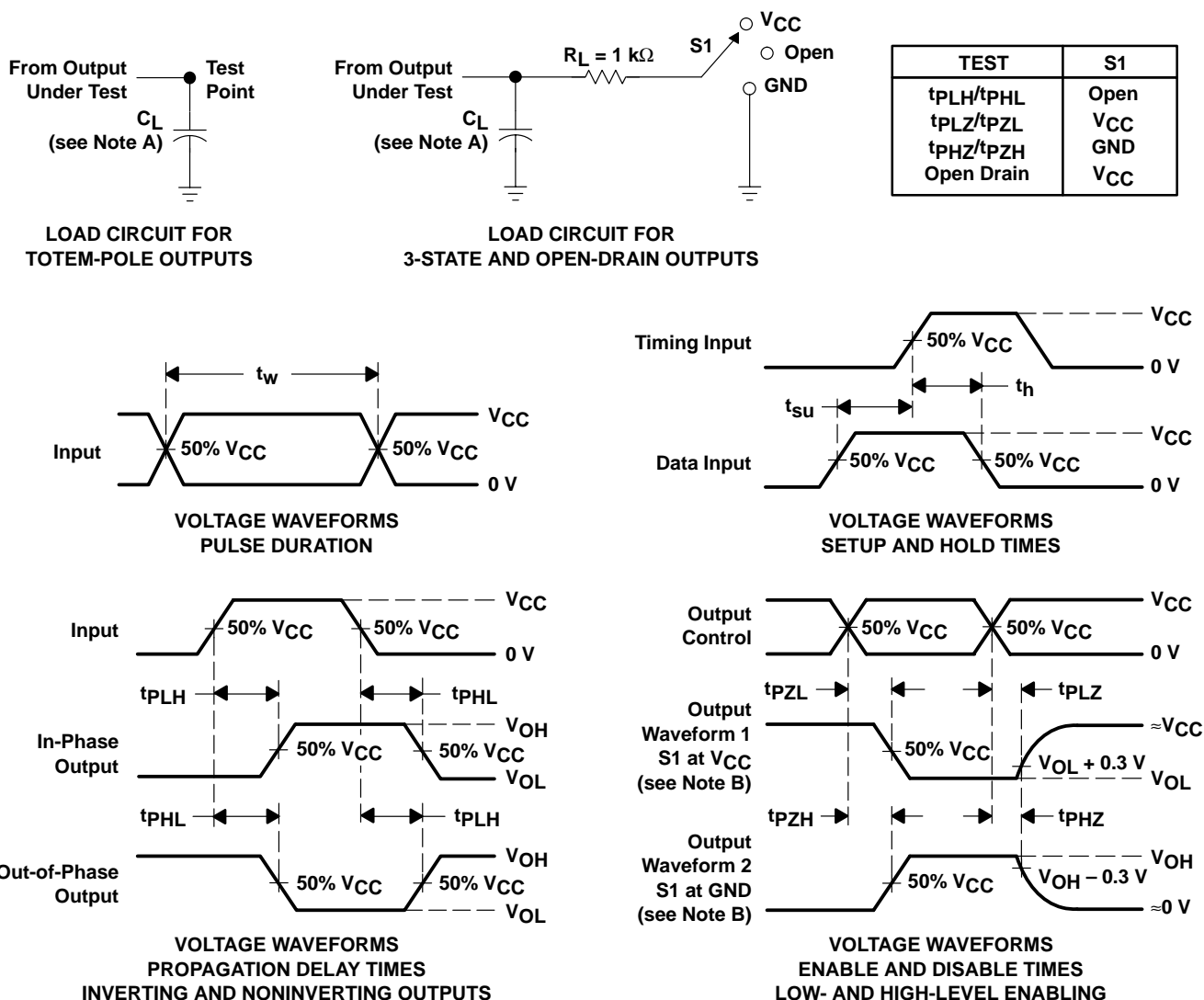
# SN54AHC574, SN74AHC574

## OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS

### WITH 3-STATE OUTPUTS

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#### PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 3\text{ ns}$ ,  $t_f \leq 3\text{ ns}$ .
  - D. The outputs are measured one at a time with one input transition per measurement.
  - E. All parameters and waveforms are not applicable to all devices.

**Figure 1. Load Circuit and Voltage Waveforms**

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-9685401Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9685401QRA	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
5962-9685401QSA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type
SN74AHC574DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI
SN74AHC574DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC574DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC574DBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC574DGVR	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC574DGVRE4	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC574DGVRG4	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC574DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC574DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC574DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC574DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC574DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC574DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC574N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AHC574NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AHC574NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC574NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC574NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC574PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC574PWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC574PWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC574PWLE	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI
SN74AHC574PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC574PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74AHC574PWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54AHC574FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54AHC574J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54AHC574W	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC574DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74AHC574DGVR	TVSOP	DGV	20	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1
SN74AHC574DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74AHC574PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC574DBR	SSOP	DB	20	2000	346.0	346.0	33.0
SN74AHC574DGVR	TVSOP	DGV	20	2000	346.0	346.0	29.0
SN74AHC574DWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74AHC574PWR	TSSOP	PW	20	2000	346.0	346.0	33.0

## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## FK (S-CQCC-N\*\*)

## LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - The terminals are gold plated.
  - Falls within JEDEC MS-004

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

## PW (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

## DGV (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194



W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only.
  - Falls within Mil-Std 1835 GDFP2-F20

## DW (R-PDSO-G20)

## PLASTIC SMALL-OUTLINE PACKAGE



4040000-4/F 06/2004

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - Falls within JEDEC MS-013 variation AC.

N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).  
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).  
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

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